Product Information

Lead-free electronic solder FELDER-ISO-Tin® “Sn96Ag+REFILL”

Lead-free refill solder for wave and selective soldering units
Sn96.9Ag3NiGe according to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289

Item No.: 551277....

Application

In order to compensate the entry of copper into the lead-free alloy Sn96Ag+ in wave soldering and selective soldering units we recommend Sn96Ag+ Refill. Hereto a regular control of the solder bath is unavoidable.

Properties

As most of the PCBs and components have copper-plated conducting paths and connections copper is flushed into the solder bath by the soldering process. In fact Sn96Ag+ has a lower dealloying quote of copper as other lead-free solders, nevertheless a copper level compensation is necessary.

Alloy:	Sn96.93Ag3.0NiGe
Melting point:	reduces in the solder bath to 217 – 220 ° C!

Analysis / tolerances

Element	Sn	Cu	Ag	Ni	Ge	Pb	Al
Content (%)	rest	0.05	3.0 ±0,2	0.05 - 0.07	0.01 – 0.015	max. 0.07	max. 0.001

Element	As	Bi	Cd	Fe	Sb	Zn
Content (%)	max. 0.03	max. 0.1	max. 0.002	max. 0.02	max. 0.1	max. 0.001

acc.: DIN EN 9453:2014

Delivery Forms

450 g (± 30 g) rods, 330 x 20 x 10 mm,
1.0 kg rods, 330 x 20 x 20 mm,
3.5 kg – blocks with hanging hole 545 x 47 x 20 mm.

Also deliverable as massive wire on spools and wire cuts for first filling.

Advices

Other alloys are included in our standard delivery program.

Status: 10/16